

WHAT IS CLAIMED IS:

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1. A cleaning substrate for cleaning and regenerating a mold including at least a protrusion on the substrate which can substantially match with and be contained within the edges of at least a mold cavity of the mold when the cleaning substrate is placed in the mold while the mold is contaminated after repeatedly packaging the semiconductor device.
 2. The cleaning substrate for cleaning and regenerating a mold of claim 1, wherein the profile of the protrusion is corresponding to the edges of the mold cavity.
 3. The cleaning substrate for cleaning and regenerating a mold of claim 1, wherein the substrate is made of paper.
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4. A cleaning substrate for cleaning and regenerating a mold, wherein the mold is contaminated after repeatedly packaging the semiconductor device by making use of a thermosetting resin, the mold comprises at least an upper mold having at least a first recess, and a lower mold having at least a second recess, and the first recess and the second recess define a mold cavity when the upper mold and the lower mold are tightly closed, the cleaning substrate comprising at least a first protrusion on the upper surface of the substrate and at least a second protrusion on the lower surface of the substrate, the first protrusion substantially matching with and being contained within the edges of the first recess of the upper mold and the second protrusion substantially matching with and being contained within the edges of the second recess of the lower mold when the cleaning substrate is placed in the mold.
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5. The cleaning substrate for cleaning and regenerating a mold of claim 4, wherein the profile of the first protrusion is corresponding to the edges of the first recess of the upper mold and the profile of the second protrusion is corresponding to the edges of the second recess of the lower mold.
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6. The cleaning substrate for cleaning and regenerating a mold of claim 4, wherein the cleaning substrate is made of paper.
 7. A method for cleaning a mold comprising:
providing a mold having at least a mold cavity;

placing a cleaning substrate in the mold cavity wherein the cleaning substrate has at least a first protrusion that can substantially match and be contained within the edges of the mold cavity;

injecting a cleaning compound into the mold cavity of the mold;

5 hardening the cleaning compound such that the cleaning compound is integrally formed with the cleaning substrate to become a molding product; and

taking the molding product out of the mold cavity by opening the mold.

8. The method for cleaning a mold of claim 7, wherein the cleaning compound is melamine resin.

10 9. The method for cleaning a mold of claim 7, wherein the mold is contaminated after repeatedly packaging the semiconductor device by making use of a thermosetting resin, the mold comprises at least an upper mold having at least a first recess, and a lower mold having at least a second recess, and the first recess and the second recess define a mold cavity when the upper mold and the lower mold are tightly closed, the
15 cleaning substrate comprises at least a first protrusion on the upper surface of the substrate and at least a second protrusion on the lower surface of the substrate, the first protrusion substantially matching with and being contained within the edges of the first recess of the upper mold and the second protrusion substantially matching with and being contained within the edges of the second recess of the lower mold
20 when the cleaning substrate is placed in the mold.

10. The method for cleaning a mold of claim 7, wherein the cleaning substrate is made of paper.